TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

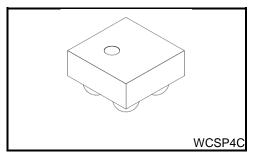
# **TCK206G, TCK207G, TCK208G**

# 0.75 V, 2A Load Switch IC with Reverse Current Blocking in Ultra Small Package

The TCK206G, TCK207G and TCK208G are 0.75 V ultra low voltage load switch ICs for a power management with slew rate control driver and reverse current blocking(SW OFF state) function.

Switch ON resistance is only 18.4 m $\Omega$  (typ.) at 0.75 V, -1.5 A condition and output current is available up to 2.0 A (DC). TCK207G and TCK208G feature output auto-discharge function.

These devices are available in 0.5 mm pitch ultra small package WCSP4C (0.9 mm x 0.9 mm, t: 0.5 mm) . Thus this devices is ideal for portable applications that require high-density board assembly such as cellular phone.



Weight: 0.9 mg (typ.)

#### **Feature**

- Low input voltage operation: V<sub>IN</sub> = 0.75 to 3.6 V
- High output current: IOUT (DC) = 2.0 A
- Low ON resistance :

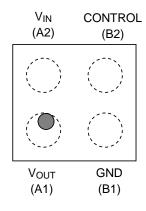
 $R_{ON} = 18.1 \text{ m}\Omega$  (typ.) at  $V_{IN} = 3.3 \text{ V}$ , -1.5 A

 $R_{ON} = 18.2 \text{ m}\Omega$  (typ.) at  $V_{IN} = 1.2 \text{ V}$ , -1.5 A

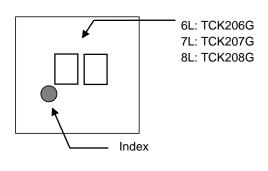
 $R_{ON} = 18.4 \text{ m}\Omega$  (typ.) at  $V_{IN} = 0.75 \text{ V}$ , -1.5 A

- · Built in Slew rate control driver
- Built in Reverse current blocking(SW OFF state)
- Built in Auto-discharge (TCK207G and TCK208G)
- Active High and Pull down connection between CONTROL and GND (TCK206G and TCK207G)
- Active Low (TCK208G)
- Ultra small package: WCSP4C (0.9 mm x 0.9 mm, t: 0.5 mm)

#### Pin Assignment(Top view)



#### Top marking



Start of commercial production 2014-06



# **Absolute Maximum Ratings (Ta = 25°C)**

Characteristics	Symbol		Unit					
Input voltage	VIN		-0.3 to 4.0 V					
Control voltage	VCT	-0.3 to 4.0 V						
Output voltage	Vout		-0.3 to V <sub>IN</sub> +0.3	V				
Output current	lout	DC	2.0	A				
		Pulse	3.0 (Note 1)	A				
Power dissipation	PD		800 (Note 2)	mW				
Operating temperature range	T <sub>opr</sub>		-40 to 85	°C				
Junction temeperature	Tj	150		150		150		°C
Storage temperature	T <sub>stg</sub>		−55 to 150	°C				

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note1: 100 µs pulse, 2% duty cycle

Note2: Rating at mounting on a board

(Glass epoxy(FR4) board dimension: 40mm x 40mm, both sides of board

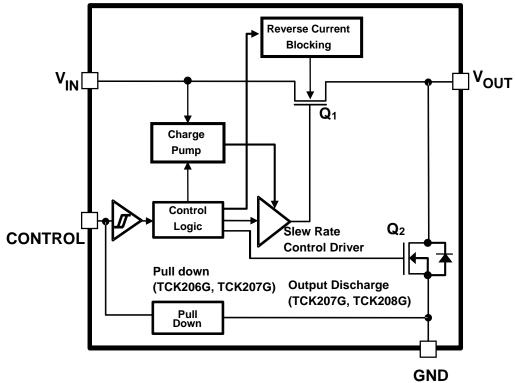
Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

2

Through hole hall : diameter 0.5mm x 28)



# **Block Diagram**



# **Function Table**

Dort number	Function						
Part number	Reverse current blocking	Output auto-discharge	Control pin connection				
TCK206G	Bulit in	N/A	Pull down (Active High)				
TCK207G	Bulit in	Bulit in	Pull down (Active High)				
TCK208G	Bulit in	Bulit in	OPEN (Active Low)				

# **Operation Logic Table**

# $0.75 \text{ V} \le \text{V}_{\text{IN}} \le 3.6 \text{V} \text{ (Ta = -40 to } 85^{\circ}\text{C)}$

		TCK206G	TCK207G	TCK208G	
	Output Q₁	ON	ON	OFF	
Control voltage "High"	Discharge Q₂	_	OFF	ON	
nigii	Reverse current block	Disable	Disable	Active	
Control voltage "Low"	Output Q₁	OFF	OFF	ON	
	Discharge Q₂	_	ON	OFF	
	Reverse current block	Active	Active	Disable	
Control voltore	Output Q <sub>1</sub>	OFF	OFF	_	
Control voltage - "OPEN"	Discharge Q <sub>2</sub>	_	ON		
	Reverse current block	Active	Active	_	



# **Electrical Characteristics**

# DC Characteristics (Ta = -40 to 85°C)

Characteristics	Symbol	Test Condition		Ta = 25°C			Ta = −40 to 85°C		Unit	
Characteristics Symbo		rest Condition		Min	Тур.	Max	Min	Max	Unit	
Input voltage	VIN	_	_			_	3.6	0.75	3.6	V
CONTROL High-level input voltage	ViH		0.9 V ≤V	İN	0.9	_	ı	0.9	-	V
CONTROL High-level input voltage	VIH		VIN < 0.9	9V	VIN	_	1	VIN	_	V
CONTROL Low-level input voltage	VIL		0.9 V ≤V	ÍN		_	0.4	-	0.4	V
CONTROL Low-level input voltage	VIL	_	VIN < 0.9	9V	_	_	0.3	1	0.3	V
Ouisseent surrent (ON state)	IQ	$V_{IN} = V_{CT} = 3.6$ V	V,	TCK206G TCK207G		22			35	
Quiescent current (ON state)		VIN = 3.6 V, VC IOUT = 0 mA	T = 0 V, TCK208G		_	22	_	_	33	μА
Otacella comment (OM OFF etch)	IQ(OFF)	VIN = 3.6 V, VCT VOUT = OPEN	= 0 V, (Note 3)	TCK206G TCK207G		0.7	_	_	5	μА
Standby current (SW OFF state)		VIN = VCT = 3.6 V		TCK208G	_					
Reverse blocking current	I <sub>RB</sub>	Vout = 3.6 V, V <sub>IN</sub> = 0 V, V <sub>CT</sub> = 0 V		_	0.1	_	_	10	μА	
	Ron	V <sub>IN</sub> = 3.3 V, I <sub>OUT</sub> = -1.5 A		_	18.1	_	_	28		
On resistance		V <sub>IN</sub> = 1.8 V, I <sub>OUT</sub> = -1.5 A		— 18.1	_	_	28			
		V <sub>IN</sub> = 1.2 V, I <sub>OUT</sub> = -1.5 A		_	18.2	_	_	28	mΩ	
		V <sub>IN</sub> = 1.0 V, I <sub>OUT</sub> = -1.5 A		_	18.2	_	_	28		
		V <sub>IN</sub> = 0.75 V, I <sub>OUT</sub> = -1.5 A		_	18.4	_	_	28		
Discharge on resistance	R <sub>SD</sub>	— (TCK207G a	and TCK20	08G)	_	380	_	_	_	Ω

Note 3: Except SW OFF state switch current (ISD<sub>(OFF):</sub>  $V_{IN} = 5.5 \text{ V}$ ,  $V_{CT} = 0 \text{ V}$ ,  $V_{OUT} = GND$ ).



# AC Characteristics (Ta = 25°C)

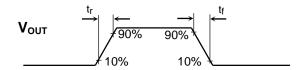
# $V_{IN} = 0.75 V$

Characteristics	Symbol	Test Condition(Figure 1)		Min	Тур.	Max	Unit
Vout rise time	tr	R <sub>L</sub> =500Ω , C <sub>L</sub> =0.1μF		_	180	_	μS
V <sub>OUT</sub> fall time	t <sub>f</sub>	R <sub>L</sub> =500Ω , C <sub>L</sub> =0.1μF	TCK207G TCK208G	1	50	-	_ μs
			TCK206G	_	80	_	
Turn on delay	ton	R <sub>L</sub> =500 $\Omega$ , C <sub>L</sub> =0.1 $\mu$ F		_	75	_	μS
Turn off delay	y toff	RL=500Ω , CL=0.1μF	TCK206G TCK207G	_	8	_	μS
·			TCK208G	_	14	_	·

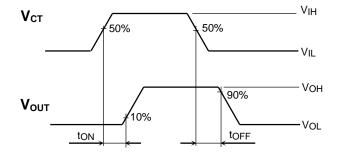
# $V_{IN} = 1.2 V$

Characteristics	Symbol	Test Condition(Figure 1)		Min	Тур.	Max	Unit
V <sub>OUT</sub> rise time	t <sub>r</sub>	R <sub>L</sub> =500Ω , C <sub>L</sub> =0.1μF		_	240	_	μS
Vout fall time	t <sub>f</sub>	R <sub>L</sub> =500Ω , C <sub>L</sub> =0.1μF	TCK207G TCK208G	_	50	_	μs
			TCK206G	_	90	_	
Turn on delay	ton	R <sub>L</sub> =500Ω , C <sub>L</sub> =0.1μF		_	65	_	μS
Turn off delay	tOFF	R <sub>L</sub> =500 $\Omega$ , C <sub>L</sub> =0.1 $\mu$ F	TCK206G TCK207G	_	8	_	μs
			TCK208G	_	13	_	

# **AC Waveform**



# TCK206G, TCK207G



#### TCK208G

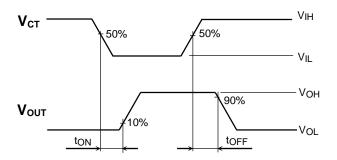


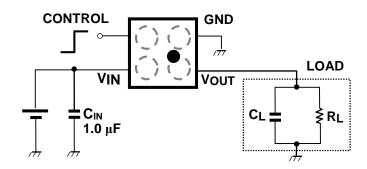
Figure 1 tr, tf, ton, toff Waveforms



## **Application Note**

### 1. Application circuit example (top view)

The figure below shows the recommended configuration for TCK206G, TCK207G and TCK208G.



#### 1) Input capacitor

An input capacitor ( $C_{IN}$ ) is necessary for the stable operation of TCK206G, TCK207G and TCK208G. And it is effective to reduce voltage drop due to sharp changes in output current and also for improved stability of the power supply. When used, place  $C_{IN}$  more than 1.0  $\mu$ F as close to  $V_{IN}$  pin to improve stability of the power supply.

#### 2) Output capacitor

An output capacitor ( $C_{OUT}$ ) is not necessary for the guaranteed operation of TCK206G, TCK207G and TCK208G. However, there is a possibility of overshoot or undershoot caused by output load transient response, board layout and parasitic components of load switch IC. In this case, an output capacitor with  $C_{OUT}$  more than  $0.1\mu F$  us recommended.

#### 3) Control pin

A control pins for TCK206G and TCK207G are both Active High and TCK208G is Active Low. These controls both the pass-through n-ch MOSFET and the discharge n-ch MOSFET (except TCK206G), operated by the control voltage and Schmitt trigger. When the control voltage level is High (Low; TCK208G), Output n-ch MOSFET is ON state and discharge n-ch MOSFET is SW OFF state. When control voltage level is Low (High; TCK208G), and the state of the MOSFETs is reversed. Also, pull down resistance equivalent to a few M $\Omega$  is connected between CONTROL and GND, thus the load switch IC is in SW OFF state even when CONTROL pin is OPEN(except TCK208G). In addition, CONTROL pin has a tolerant function such that it can be used even if the control voltage is higher than the input voltage.

#### 2. Reverse current blocking

Reverse current blocking(SW OFF state) function is designed in these products. This function is active at output n-ch MOSEFT turned off.

However these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.



# 3. Power Dissipation

Board-mounted power dissipation ratings for TCK206G, TCK207G and TCK208G are available in the Absolute Maximum Ratings table

Power dissipation is measured on the board condition shown below.

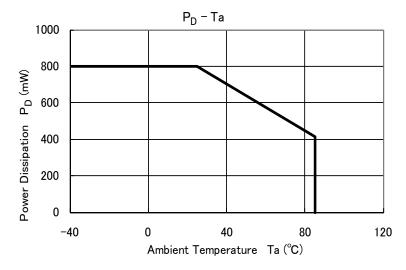
[The Board Condition]

Board material: Glass epoxy (FR4)

Board dimension: 40mm x 40mm (both sides of board), t=1.8mm

Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5mm x 28

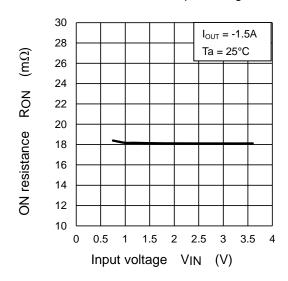


Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc. and applying the appropriate derating for allowable power dissipation during operation.

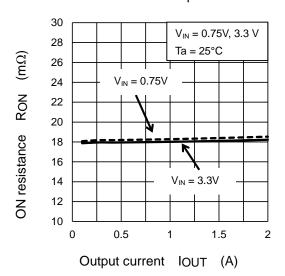
# **Representative Typical Characteristics**

# 1) ON resistance

ON resistance vs Input voltage

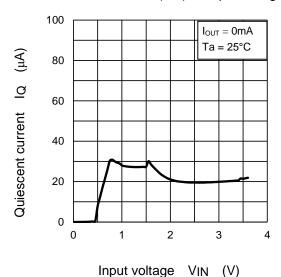


# ON resistance vs Output current



# 2) Quiescent current

Quiescent current(ON) vs Input voltage



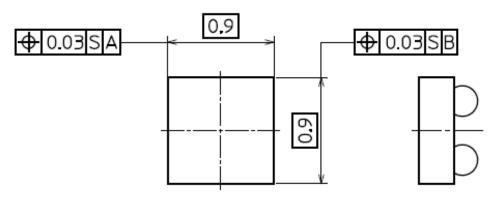
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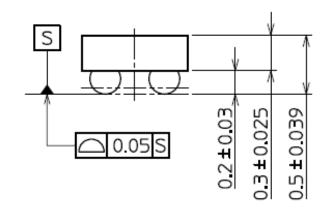


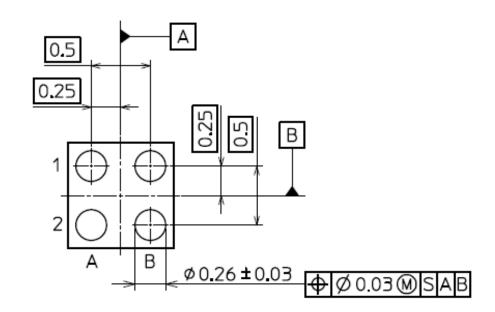
# Package dimension

Unit: mm

WCSP4C



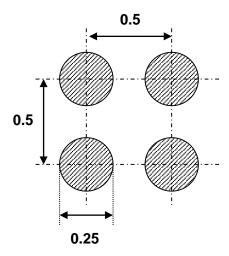




Weight: 0.9 mg (typ.)

Land pattern dimensions (for reference only)

Unit:mm





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